

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC026NE2LS5	**Issued**	28. January 2020
MA#	MA005350314		
Package	PG-TDSON-8-45	**Weight***	117.68 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.210	0.18	0.18	1788	1788
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		321	
	non noble metal	copper	7440-50-8	37.762	32.09	32.13	320880	321297
wire	non noble metal	copper	7440-50-8	0.022	0.02	0.02	183	183
encapsulation	organic material	carbon black	1333-86-4	0.088	0.07		748	
	plastics	epoxy resin	-	6.951	5.91		59068	
	inorganic material	silicondioxide	60676-86-0	36.956	31.40	37.38	314031	373847
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12335	12335
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1407	1407
solder	non noble metal	tin	7440-31-5	0.007	0.01		63	
	noble metal	silver	7440-22-4	0.009	0.01		79	
	non noble metal	lead	7439-92-1	0.355	0.30	0.32	3014	3156
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		190	
	non noble metal	copper	7440-50-8	22.292	18.94	18.97	189423	189670
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.62	9.63	96192	96317
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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